

ELECTRONIC PACKAGING APPARATUS AND METHOD

Abstract of the Disclosure

5 An electronic assembly includes a substrate, a device attached to the
substrate, and a thermally conductive heat spreader covering the device and at least
a portion of the substrate. A metal substantially fills the space between the device
and the thermally conductive heat spreader. A method includes attaching at least
one die to a substrate, placing a thermally conductive heat spreader over the die, and
10 injecting a molten metal material into the space between the thermally conductive
heat spreader and the die.

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